

# SEMICONDUCTOR COMPONENT AND METHOD OF MANUFACTURING SAME

## ABSTRACT OF THE DISCLOSURE

5           In one embodiment of the invention, a semiconductor component includes: a leadframe (110, 210, 310, 410) having a surface (111, 211, 311, 411); an integrated passive component (120, 220, 320, 420) located above the surface of the leadframe; a semiconductor chip (130, 230, 330, 430) electrically coupled to the integrated passive component and located above the surface of the leadframe; and a mold compound (140, 240, 340, 440) disposed around the semiconductor  
10 chip, the integrated passive component, and the leadframe. A portion (112, 212, 312, 412) of the leadframe is exposed outside of the mold compound. The integrated passive component comprises a passive device (121, 221, 321, 421). A direction (190, 290, 390, 490) perpendicular to the surface of the leadframe is a vertical direction, and the semiconductor chip, the integrated passive component, and the leadframe are arranged vertically with respect to each other.